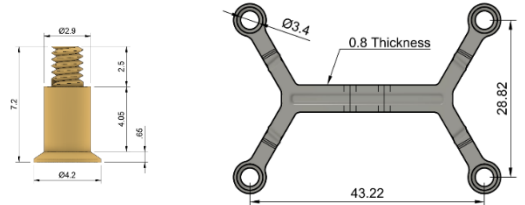


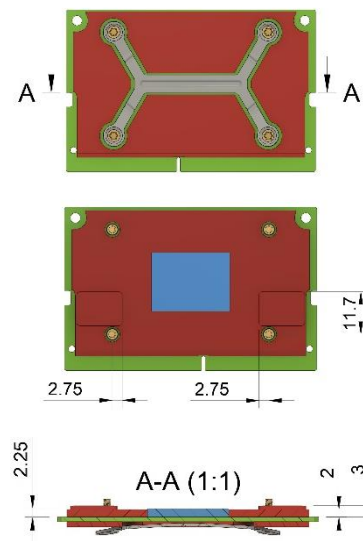
### Heatsink / Heatspreader / Leaf spring

The Xavier NX leaf spring kits for secure mounting of cooling solutions. This ensures optimal thermal interface while minimizing the risk of damaging the module.



#### Implementation guidelines

- Refer to Nvidia Jetson Xavier NX Thermal Design Guide for thermal dissipation requirements
- Use M2x0.4 thread with at least 3mm depth fully formed thread in heatspreader/sink
- Recommended material for heatsink is aluminum or copper
- Use intermediate heat transfer compound (paste or pad), do not screw the module directly to heatsink/heat spreader or case
- When using heatspreader use thermal pad >0.5mm between heatspreader and case to ensure thermal conductivity
- Do not cover the module envelope
- Use <0.15Nm for M2 screws
- Handle module with care during assembly (ESD)
- Ensure correct orientation of the spring. The leaf spring should only contact the module in the middle
- SO-DIMM connector spacers must be used to reduce stress on the PCB



RED: module envelope, keep out zone for component clearance  
 BLUE: Processor die  
 GREEN: PCB + underside  
 The envelope for thermal solution 3D model is available in the Nvidia developer download area



Heatsink with fan



Heatspreader

#### Leaf spring kit XAVIER NX:

Each kit includes

- Leaf spring (155-0892-000)
- 4 screws (155-0876-000)

#### Cooling kit XAVIER NX:

Each kit includes

- Leaf spring (155-0892-000)
- 4 screws (155-0876-000)
- Heatsink with integrated fan (095-0073-000)

SKU	Kit
70799	Leaf spring Kit XAVIER NX
70797	Cooling kit XAVIER NX
70753-335	Heatspreader 50.1x40x3.35mm
70753-435	Heatspreader 50.1x40x4.35mm
70753-455	Heatspreader 50.1x40x4.55mm
70798	Heatsink with fan (095-0073-000)

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